

WHAT IS CLAIMED IS:

1. A heat dissipation structure, comprising:
a heat sink, installed on a heat generating electronic device;
at least one heat pipe, having a proximal end located on the heat sink and a
5 distal end extends outside of the heat sink, wherein the heat pipe includes a wick
structure and a working fluid therein;
a set of fins connected to the distal end of the heat pipe;
at least one thermal conductor block installed on the heat sink and adjacent
to the heat pipe, the thermal conductor block is operative to store thermal energy.
- 10 2. The structure of Claim 1, wherein the heat sink further comprises an
extension extends towards the set of fins.
3. The structure of Claim 1, wherein the extension extends over the set of
fins to form a guide portion.
4. The structure of Claim 1, wherein the electronic device includes a
15 central processing unit.
5. The structure of Claim 1, comprising two thermal conductor blocks at
two sides of the heat pipe.
6. The structure of Claim 1, wherein the thermal conductor includes a
recessed channel for accommodating the heat pipe therein.
- 20 7. The structure of Claim 1, wherein the thermal conductor block
includes a U-shape plate on which a non-through slot is formed for embedding the
heat pipe therein.
8. The structure of Claim 1, wherein the thermal conductor block is
fabricated from copper.
- 25 9. The structure of Claim 1, wherein the thermal conductor block is
fabricated from aluminum.
10. The structure of Claim 1, wherein the thermal conductor block is
fabricated from alloy of copper and aluminum.

11. The structure of Claim 1, wherein the thermal conductor block is fabricated in a form of reinforcing rib.